



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Chuen Rong Leu et al.  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP  
ASSEMBLY WITH AN EMBEDDED METAL PILLAR  
Serial No.: 10/719,823 Filed: November 21, 2003  
Examiner: Dang, P. Group Art Unit: 2818  
Atty. Docket No.: BDG024-1

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COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER ALLOWANCE**

Dear Sir:

Please amend the application as follows.

The Specification Amendments begin on page 2.

The Remarks begin on page 3.